



ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

### Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type\*  
Distribute

Declaration Class\*  
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

#### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Nov 07, 2014 02:03 PM
<b>Contact Name *</b> David Lancaster	Title - Contact Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	Title - Representative Product Ecology	<b>Phone - Representative *</b> 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
H11L1M	H11L1M	DIPW-6.csv			Subcon	0.537379	g	Each

#### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	NA	Not Applicable		Not Applicable

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
<p>Exemption List Version EL-2011/534/EU none</p>		

**Declaration Signature**

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name DIPW-6.csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Encapsulation	Thermoplastics	414.67	Supplier		Silica, vitreous	290.27	60676-86-0	540158
Lead Frame	Copper & its alloys	108.322	Supplier		Copper	105	7440-50-8	195393
			Supplier		Iron	2.48	7439-89-6	4615
			Supplier		Phosphorus	0.032	7723-14-0	60
			Supplier		Silver	0.68	7440-22-4	1265
			Supplier		Zinc	0.13	7440-66-6	242
Plating	Other Nonferrous metals & alloys	6.7	Supplier		Tin	6.7	7440-31-5	12468
Wire Bond	Precious metals	0.149	Supplier		Gold	0.149	7440-57-5	277
Chip	Other inorganic materials	4.043	Supplier		Gallium Arsenide	0.283	1303-00-0	527
			Supplier		Silicon	3.76	7440-21-3	6997
Coupling Gel	Other Organic Materials	1.83	Supplier		Dimethyl Cyclosiloxanes	0.183	69430-24-6	1182
			Supplier		Methyltrimethoxysilane	1.647	1185-55-3	1652
Die Attach	Other Organic Materials	1.665	Supplier		Phenolic resin	0.415	54208-63-8	772
			Supplier		Silver	1.25	7440-22-4	2326
Encapsulation	Thermoplastics	414.67	B	Antimony/Antimony Compounds	Antimony Trioxide	12.4	1309-64-4	23075
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	16.6	6386-73-8	30891
			Supplier		Epoxy Resin	95.4	29690-82-2	177528